

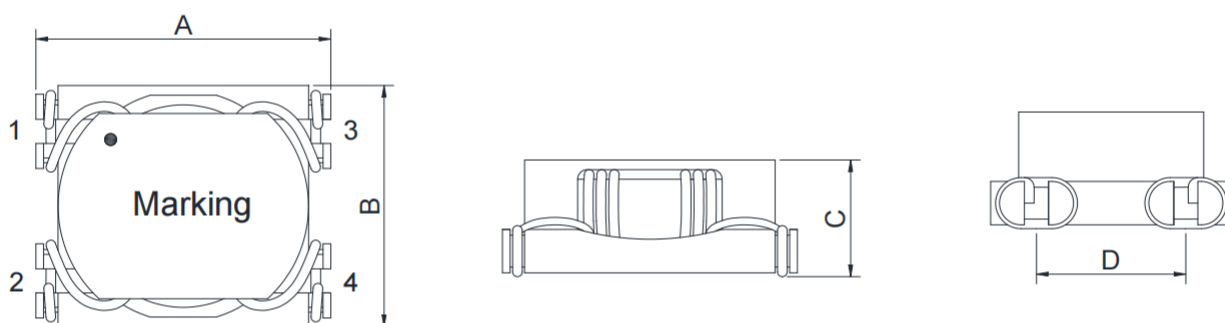
Common mode filter

◆ ORDERING CODE:

SMW 3013 S 811 Q T T
 (1) (2) (3) (4) (5) (6) (7)

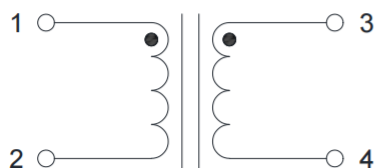
- (1): Series Type
 (2): Chip Size(mm):L x H
 (3): Material Type
 (4): Nominal Impedance:0.81mH=811
 (5): Internal Code
 (6): Company Code
 (7): Packaging: T: Taping&Reel

◆ DIMENSION (: mm)

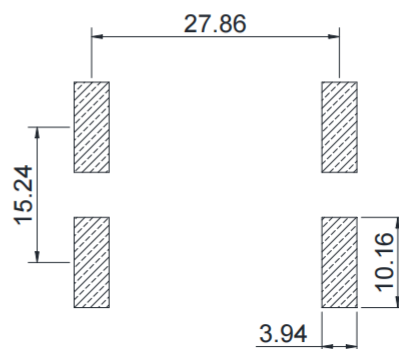


A	B	C	D
31.0 Max	25.4 Max	12.7 Max	15.24 ± 0.3

◆ SCHEMATIC:



◆ REFERENCE LAND PATTERN



◆ ELECTRONUC CHARACTERISTICS

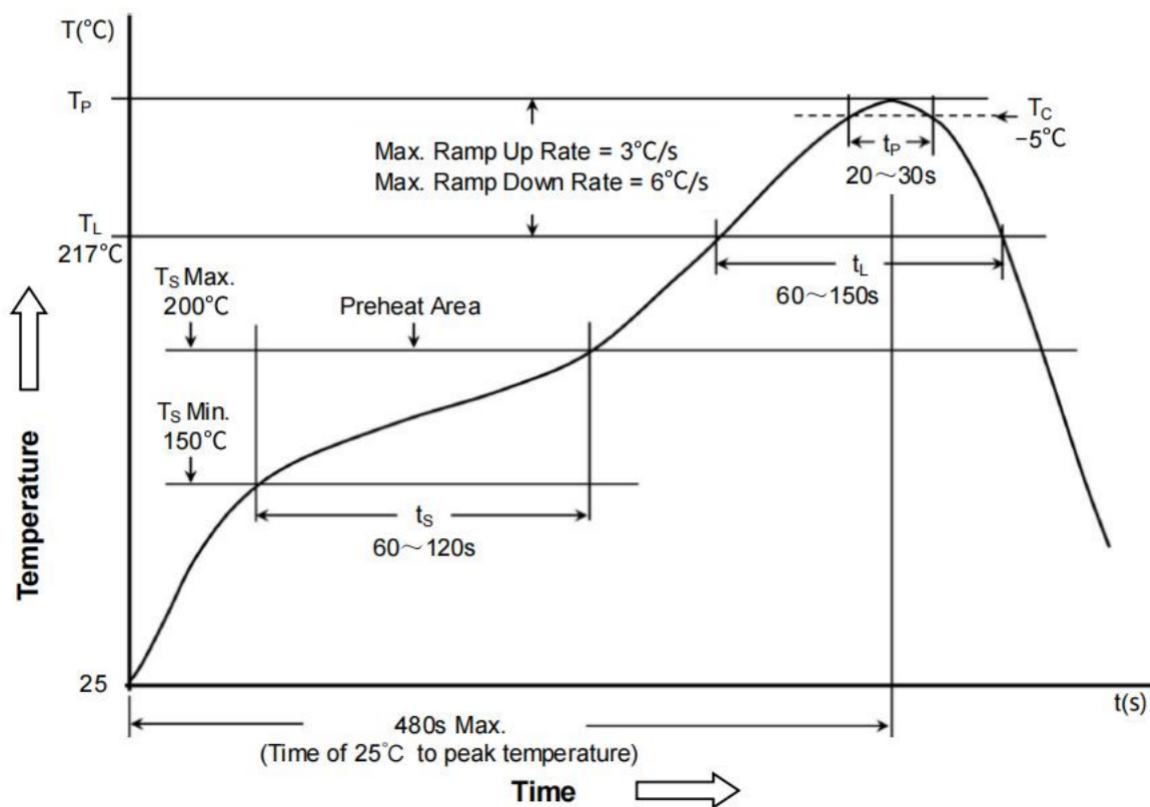
P/N	Inductance 1-2=3-4 (mH) @10KHz/0.1V	Tums Ratio $\pm 2\%$ 1-2:3-4	DCR (m Ω)Max 1-2=3-4	Rated Current (A) Max	Impedance (K Ω) Max 0.99MHz	Hi-Pot 1,2-3,4 (V)AC 1mA/3S
SMW3013S811QTT	0.81 Typ/0.52 Min	1:1	14.0	6.0	4.82 Typ	1000

Note:

- (1).All data is tested based on 25°C ambient temperature
- (2).Rated current the value of DC current when the temperature rise is AT40°C(Ta=25°C)
- (3).Operating Temperature:-40°C to +125°C(Temperature rise included)
- (4).Storage condition:Temperature -25 to +40°C RH $\leq$ 75%

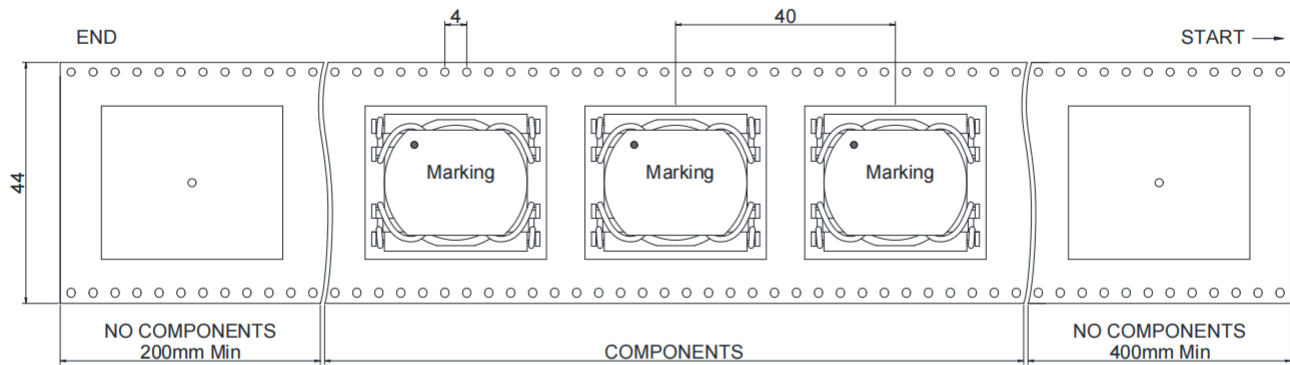
◆ Soldering Specification

Reflow Profile for SMT Components



◆ Packing Specification

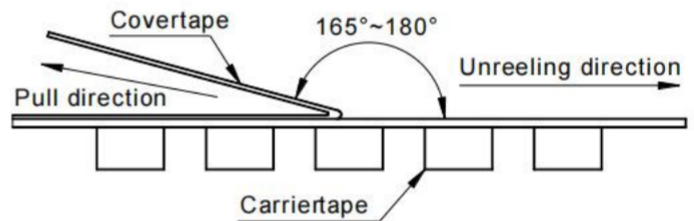
Tape Direction (mm)



Cover Tape Peel Off Condition

Cover tape peel force shall be 10g to 130g

Reference peel speed 300 ± 10 mm/min



Quantity: 100PCS/Reel